

CLAIMS:

1. Dip soldering apparatus comprising a reservoir for solder into which component leads are dipped, wherein a surface which is wetted by the solder is provided closely adjacent to and facing the leads during dipping.
2. Apparatus for soldering two or more leads to a circuit board, the apparatus including molten solder and the leads being dipped into the molten solder to solder them to the circuit board, wherein a surface which is wetted by the solder is provided in the molten solder in the vicinity of the dipped leads.
3. Dip soldering apparatus comprising a nozzle through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein a surface which is wetted by the solder is provided in the solder at the nozzle outlet.
4. Apparatus as claimed in claim 3, wherein the wetted surface is provided by a member which is below the level of the solder surface as the solder flows through the nozzle outlet.
5. Apparatus as claimed in claim 3, wherein the surface is provided by a member which is movable relative to the solder surface.

6. A method of dip soldering a plurality of closely spaced leads to a circuit board, the leads projecting from an underside of the board, the method comprising dipping the leads into a surface of molten solder to coat the leads and an adjacent circuit track with solder and withdrawing the leads from the solder surface, wherein a surface which is wetted by the molten solder is provided adjacent the leads, the wetted surface projecting through the solder surface as the leads are withdrawn from the solder.

7. A method as claimed in claim 6, wherein the solder surface is lowered to effect withdrawal of the leads from the solder.